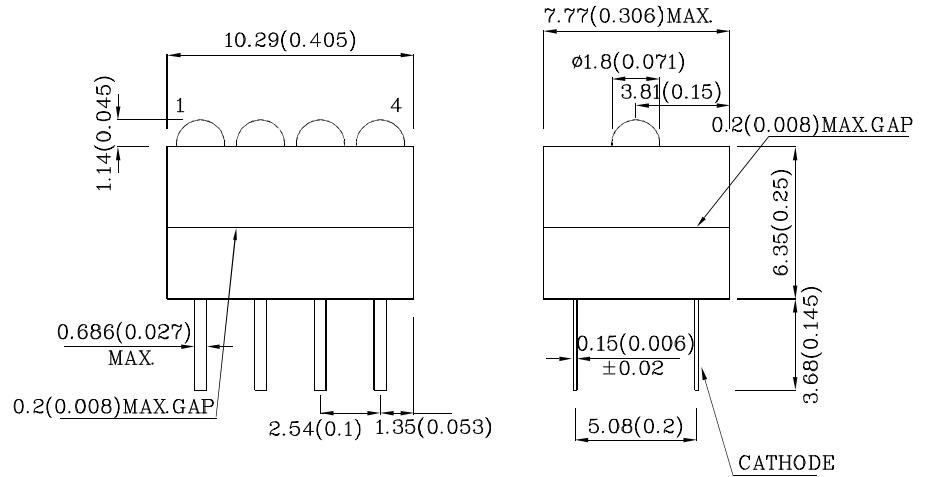


Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- Reliable & robust
- Custom color combinations available
- RoHS Compliant



Package Schematics

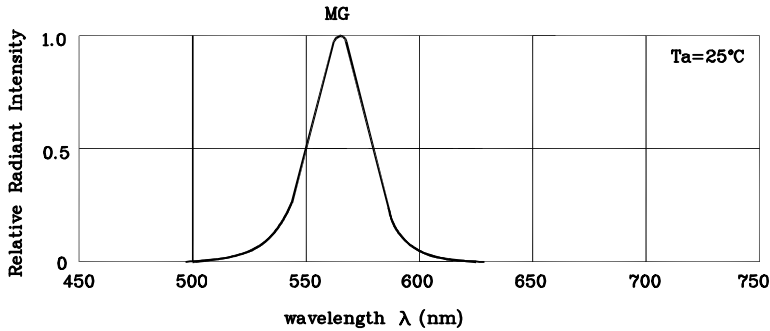


- Notes:
1. All dimensions are in millimeters (inches).
 2. Tolerance is ±0.25(0.01") unless otherwise noted.
 3. Specifications are subject to change without notice.

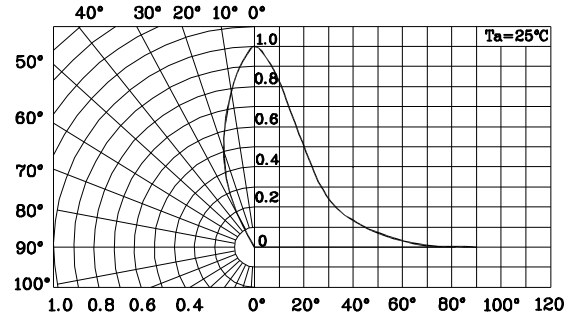
Absolute Maximum Ratings (T _A =25°C)		MG (GaP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	140	mA
Power Dissipation	P _D	62.5	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (T _A =25°C)		MG (GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	2.2	V
Forward Voltage (Max.) (I _F =20mA)	V _F	2.5	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λ _P	565	nm
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λ _D	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λ _P	Viewing Angle 2θ 1/2
				min.	typ.		
XNG4ZMG46D	Green	GaP	Green Diffused	8	14	565	40°

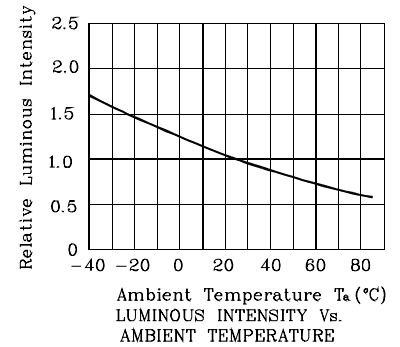
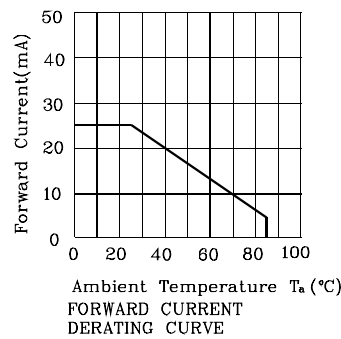
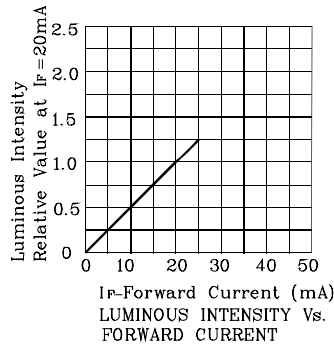
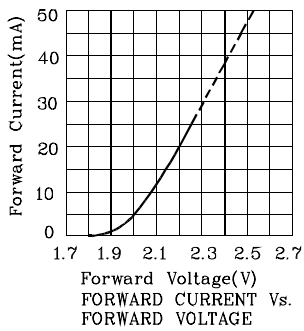


RELATIVE INTENSITY Vs. WAVELENGTH

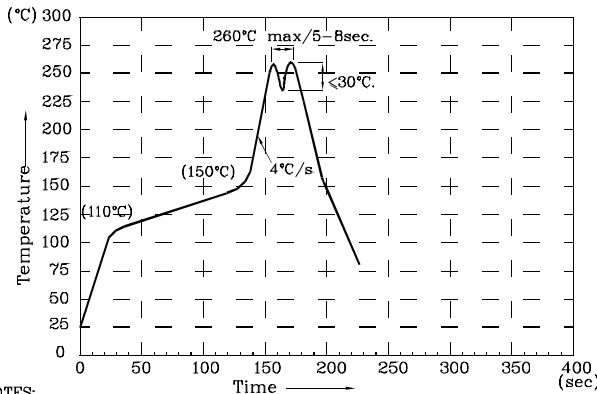


SPATIAL DISTRIBUTION

❖ MG



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

- 1.Recommend the wave temperature 245 $^\circ\text{C}$ ~260 $^\circ\text{C}$.The maximum soldering temperature should be less than 260 $^\circ\text{C}$.
- 2.Do not apply stress on epoxy resins when temperature is over 85 $^\circ\text{C}$.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105 $^\circ\text{C}$.
- 5.No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

